

Abstract:

The present invention relates to a resin composition containing an epoxy resin, an amine-type curing agent, an organophosphorus compound having a structure represented by formula 1 and an organic solvent, wherein the epoxy resin and the organophosphorus compound has been compounded at a temperature of 50°C or lower. The resin composition has enough flame retardancy without containing any halogen-  
10 containing flame retarder, has good heat resistance and good chemical resistance, and causes no problems with respect to reaction stability or curability caused by consumption of an epoxy resin through a reaction occurring during compounding of the resin composition.

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